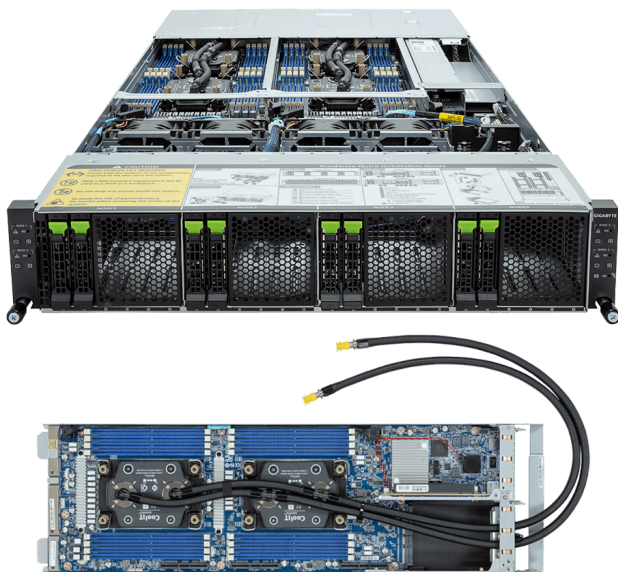
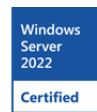


# H263-S63-LAW1

High Density Server - 5th/4th Gen Intel® Xeon® Scalable -  
2U 4-Node DP 8-Bay Gen4 NVMe/SATA/SAS 3000W DLC



## Key Features

- Direct liquid cooling solution
- 2U 4-node rear access server system
- Dual 5th/4th Gen Intel® Xeon® Scalable Processors per node
- Dual Intel® Xeon® CPU Max Series per node
- 8-Channel DDR5 RDIMM, 16 x DIMMs per node
- 1 x CMC port
- 8 x 2.5" Gen4 NVMe/SATA/SAS hot-swap bays
- 4 x M.2 slots with PCIe Gen4 x4 interface **(optional)**
- 4 x LP PCIe Gen5 x16 slots
- 4 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Dual 3000W 80 PLUS Titanium redundant power supply

## Applications

High-Performance Computing Server, High Converged Server...

## Specification

<b>Dimensions</b>	2U 4-Node - Rear access (W440 x H87.5 x D850 mm)	<b>PCIe Expansion Slots</b>	4 x LP PCIe Gen5 x16 4 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
<b>Motherboard</b>	MS63-HD1	<b>I/O Ports</b>	<b>Front:</b> 1 x CMC status LED, 1 x CMC reset button <b>Rear:</b> 8 x USB 3.2 Gen1, 4 x VGA, 4 x MLAN, 1 x CMC port
<b>CPU</b>	5th Generation Intel® Xeon® Scalable Processors 4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Dual processor per node, TDP up to 385W	<b>Backplane Board</b>	PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s
<b>OS Compatibility</b>	<a href="#">OS Support List</a>	<b>TPM</b>	1 x TPM header (SPI), Optional TPM2.0 kit: CTM010
<b>Socket</b>	8 x LGA 4677 (Socket E)	<b>Power Supply</b>	Dual 3000W 80 PLUS Titanium redundant power supply Available for 2+1 redundant power supply configuration <b>(optional)</b> AC Input: 100-240V  *The system power supply requires C19 power cord.
<b>Chipset</b>	Intel® C741	<b>System Fans</b>	4 x 80x80x38mm
<b>Memory</b>	8-Channel DDR5 RDIMM, 64 x DIMMs [5th Gen Intel Xeon] Up to 5600 MT/s [4th Gen Intel Xeon] Up to 4800 MT/s [Intel Xeon Max Series] Up to 4800 MT/s	<b>Operating Properties</b>	Operating: 10°C to 40°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)  *To ensure system stability and prevent condensation, when the relative humidity exceeds 50%, the coolant inlet temperature must be higher than the dry-bulb temperature and it should not exceed 45°C.
<b>LAN</b>	4 x 10/100/1000 Mbps Management LAN 1 x CMC Management LAN <sup>[1]</sup>  <sup>[1]</sup> Please refer to optional parts for ring topology support.	<b>Packaging Content</b>	1 x H263-S63-LAW1 4 x CoolIT CPU cold plate loops 24 x Carriers 1 x 3-Section Rail kit
<b>Video</b>	Integrated in ASPEED® AST2600 x 4 - 4 x VGA ports	<b>Ordering Part Numbers</b>	6NH263S63DR000LBW1*
<b>Storage</b>	<b>Front hot-swap:</b> 8 x 2.5" Gen4 NVMe/SATA/SAS <sup>[1]</sup> <b>Optional internal M.2:</b> 4 x M.2 (2280/22110), PCIe Gen4 x4  <sup>[1]</sup> SAS card is required to support SAS drives.	<b>Optional Parts</b>	- M.2 riser card - CMTMP061: 9CMTMP061NR-00* - Ring topology kit (10-kit package): 6NH263S62S1000AAN11 - GIGABYTE CPU cold plate loop: 25H26-3S62000-E01X <b>(QPA:4)</b> - GIGABYTE 2U4N Manifold: 25H27-3Z80000-E07X <b>(1 set per rack)</b> - CoolIT leak sensor board: 6NH263S62S1000LAN11 <b>(QPA:4)</b>
<b>RAID</b>	Intel® SATA RAID 0/1 Onboard VROC key header Support <b>optional</b> RAID add-in cards		



Learn more at: <https://www.gigabyte.com/Enterprise>

\* All specifications are subject to change without notice. Please visit our website for the latest information.

\* All trademarks and logos are the properties of their respective holders.

© 2026 Giga Computing Technology Co., Ltd. All rights reserved.

Last updated: Jan 27, 2026

Designed by

